Special Issue

Deep Learning Application in Medical Image Analysis

Message from the Guest Editor

With the rapid development of computer vision and artificial intelligence, medical image analysis and computer-aided diagnosis have become emerging interdisciplinary subjects in medicine and computer science. The massive data volume and its objective and quantifiable characteristics in medical images are suitable for the application scenario of deep learning, making medical image analysis the most promising field for implementing computer vision. However, there are still many problems to be solved, such as reducing reliance on large-scale data, improving model generalization ability, and enhancing interpretability. This Special Issue aims to highlight new and innovative work focused on deep learning applications in medical image analysis. We encourage high-quality research in medical image feature extraction, segmentation, detection, classification, registration, 3D reconstruction, and computer-aided medical diagnosis. In addition, quality manuscripts are welcome in medical-image-based radiomics, medical image privacy protection, and other cutting-edge research.

Guest Editor

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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